Docket No. AMENDMENT TRANSMITTAL LETTER 2019-0214P Application No. Filing Date Examiner Art Unit September 5, 2003 M. N. Trinh 3729 10/655,223-Conf. #6995

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TENT & TRAD

Applicant(s): Huei-Jen CHEN et al.

METHOD FOR FABRICATING A SUBSTRATE, INCLUDING A PLURALITY OF CHIP In ention: PACKAGE SUBSTRATES

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Transmitted herewith is an amendment in the above-identified application.

		CLAIM	S AS AMENI	DED	
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	3	- 20 =	0	х	
Independent Claims	1	- 3 =	0	X	
Multiple Depend	dent Claims (ch	eck if applicabl	e)	-	
Other fee (pleas	e specify):				
TOTAL ADDIT	IONAL FEE FO	OR THIS AME	NDMENT:		0.00
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Joe McKinney Attorney Reg. N				Dated:	May 5, 2006
BIRCH, STEW, 8110 Gatehous Suite 100 East P.O. Box 747 Falls Church, V (703) 205-8026	ART, KOLASC se Road 'irginia 22040-		LP		





Docket No.: 2019-0214P

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Huei-Jen CHEN et al.

Application No.: 10/655,223

Filed: September 5, 2003

For: METHOD FOR FABRICATING A

SUBSTRATE, INCLUDING A PLURALITY

OF CHIP PACKAGE SUBSTRATES

Confirmation No.: 006995

Art Unit: 3729

Examiner: M. N. Trinh

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 May 5, 2006

Sir:

INTRODUCTORY COMMENTS

In reply to the Office Action dated February 9, 2006, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

Amendments to the Specification;

Amendments to the Abstract;

Amendments to the Claims; and

Remarks.